



# KIPSAT 1.0 / 2.1 / 2.2

## HPDP

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European Space Agency

# KIPSAT 1.0 / 2.1 / 2.2



- ✓ Activity title: KIPSAT (**Key IPs** for **SAT**ellites)
- ✓ Budget / program: TRP ~ 4.5M€
- ✓ Duration: 9 years (kick off Phase1.0 in February 2008)
- ✓ Prime and subco:
  - ✓ Prime: STMicroelectronics Grenoble
  - ✓ Subco: ISD, Thales, Airbus
- ✓ Objectives:
  - ✓ To harden the commercial ST 65nm ASIC technology for Space applications
  - ✓ To harden high speed serial links (HSSLP IP operating @ 6.25Gbps)
  - ✓ To evaluate reliability and radiation effects through dedicated test vehicles
  - ✓ To validate ST design flow through real application cases



# HPDP



✓ Activity title: HPDP (**H**igh **P**erformance **D**ata **P**rocessor)

✓ Budget / program: GTF ~ 480K€

✓ Duration: 7.5 years (Kick off September 2009)

✓ Prime and subco:

✓ Prime: ISD

✓ Subco: Airbus Ottobrunn

✓ Objectives:

- ✓ To develop a high performance DSP processor capable of delivering 40 Giga operations per second (ALUs 16bits fixed point)
- ✓ To develop a highly parallel architecture in order to reach the performance level targeted (40 ALUs in parallel)
- ✓ To keep the clock frequency to a moderate value (300 MHz) to mitigate the power consumption
- ✓ To emulate floating point operations for specific applications where high dynamic range is needed
- ✓ To have a scalable architecture (multi-chips on the same board)
- ✓ To allow dynamic in-flight reconfiguration
- ✓ To allow electric interfacing with common standards (SpaceWire)
- ✓ Low complexity package to allow easy PCB mounting (CGA 625)

